

# TinyLogic UHS D-Type, Flip-Flop with Preset and Clear

# NC7SZ74

#### Description

The NC7SZ74 is a single, D-type, CMOS flip-flop with preset and clear from **onsemi** ultra high-speed series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive, while maintaining low static power dissipation over a very broad  $V_{\rm CC}$  operating range of 1.65 V to 5.5 V  $V_{\rm CC}$ . The inputs and outputs are high impedance when  $V_{\rm CC}$  is 0 V. Inputs tolerate voltages up to 5.5 V, independent of  $V_{\rm CC}$  operating voltage.

The signal level applied to the D input is transferred to the Q output during the positive–going transition of the CLK pulse.

#### **Features**

- Ultra-High Speed: t<sub>PD</sub> 2.6 ns (Typical) into 50 pF at 5 V V<sub>CC</sub>
- High Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise/EMI Reduction Circuitry

#### **CONNECTION DIAGRAM**

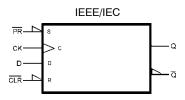


Figure 1. Logic Symbol



US8 CASE 846AN



UQFN8 1.6X1.6, 0.5P CASE 523AY

#### MARKING DIAGRAMS

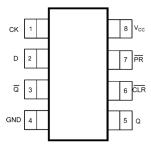




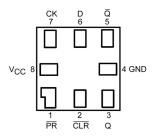
SZ74, N9 = Specific Device Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Wee

KK = 2-Digit Lot Run Traceability Code XY = 2-Digit Date Code Format Z = Assembly Plant Code

#### **PIN CONFIGURATIONS**



**USB (Top View)** 



MicroPak™ (Top Through View)

# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 6 of this data sheet.

1

## NC7SZ74

## **PIN DEFINITIONS**

Pin # US8	Pin # MicroPak	Name	Description
1	7	CK	Clock Pulse Input
2	6	D	Data Input
3	5	Q	Flip-Flop Output
4	4	GND	Ground
5	3	Q	Flip-Flop Output
6	2	CLR	Direct Clear Input
7	1	PR	Direct Preset Input
8	8	Vcc	Supply Voltage

## **FUNCTION TABLE**

	Inp	uts		Out		
CLR	PR	D	СК	Q	Q	Function
L	Н	Х	Х	L	Н	Clear
Н	L	Х	Х	Н	L	Preset
L	L	Х	Х	Н	Н	
Н	Н	L	<b>↑</b>	L	Н	
Н	Н	Н	<b>↑</b>	Н	L	
Н	Н	Х	↓	Q <sub>n</sub>	$\overline{Q}_n$	No Change

H = HIGH Logic Level

Qn = No change in data

X = Immaterial

↓= Falling Edge

L = LOW Logic Level

Z = High Impedance

↑ = Rising Edge

# **ABSOLUTE MAXIMUM RATINGS**

Symbol	Param	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage		-0.5	6.5	V
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	=	-50	mA
I <sub>OUT</sub>	DC Output Source/Sink Current	=	±50	mA	
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current			±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
T <sub>J</sub>	Junction Temperature Under Bias		=	+150	°C
T <sub>L</sub>	Junction Lead Temperature (Soldering,	10 Seconds)	=	+260	°C
P <sub>D</sub>	Power Dissipation in Still Air	US8 MicroPak-8	- -	500 539	mW
ESD	Human Body Model: JEDEC:JESD22-A114			4000	V
	Charge Device Model: JEDEC:JESD22	2-C101	-	2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### NC7S774

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply Voltage Operating		1.65	5.50	V
	Supply Voltage Data Retention		1.50	5.50	1
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage	Active State	0	Vcc	V
		3-State	0	5.5	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	V <sub>CC</sub> = 1.8 V, 2.5 V ±0.2 V	0	20	ns/V
		V <sub>CC</sub> = 3.3 V ±0.3 V	0	10	1
		V <sub>CC</sub> = 5.0 V ±0.5 V	0	5	1
T <sub>A</sub>	Operating Temperature		-40	+85	°C
$\theta_{JA}$	Thermal Resistance	US8		250	°C/W
		MicroPak-8		232	1

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NOTE: Unused inputs must be held HIGH or LOW. They may not float.

## DC ELECTRICAL CHARACTERISTICS

				T,	$T_A = +25^{\circ}C$			T <sub>A</sub> = -40 to +85°C	
Symbol	Parameter	Vcc	Conditions	Min	Тур	Max	Min	Max	Units
$V_{IH}$	HIGH Level Control	1.65 to 1.95		0.65 V <sub>CC</sub>			0.65 V <sub>CC</sub>		V
	Input Voltage	2.30 to 5.50		0.70 V <sub>CC</sub>			0.70 V <sub>CC</sub>		
$V_{IL}$	LOW Level Control	1.65 to 1.95				0.35 V <sub>CC</sub>		0.35 V <sub>CC</sub>	V
	Input Voltage	2.30 to 5.50				0.30 V <sub>CC</sub>		0.30 V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	1.65	VIN = VIH,	1.55	1.65		1.55		V
	Voltage	2.30	I <sub>OH</sub> = -100 μA	2.20	2.30		2.20		
		3.00		2.90	3.00		2.90		
		4.50		4.40	4.50		4.40		
		1.65	I <sub>OH</sub> = -4 mA	1.29	1.52		1.29		
		2.30	I <sub>OH</sub> = -8 mA	1.90	2.15		1.90		
		3.00	I <sub>OH</sub> = -16 mA	2.40	2.80		2.40		
		3.00	I <sub>OH</sub> = -24 mA	2.30	2.68		2.30		
		4.50	I <sub>OH</sub> = -32 mA	3.80	4.20		3.80		
V <sub>OL</sub>	LOW Level Control	1.65	$V_{IN} = V_{IH}$			0.10		0.10	V
	Output Voltage	2.30 I <sub>OL</sub> = 100 μA	I <sub>OL</sub> = 100 μA			0.10		0.10	
		3.00				0.10		0.10	
		4.50				0.10		0.10	
		1.65	I <sub>OL</sub> = 4 mA		0.10	0.24		0.24	
		2.30	I <sub>OL</sub> = 8 mA		0.10	0.30		0.30	
		3.00	I <sub>OL</sub> = 16 mA		0.15	0.40		0.40	
		3.00	I <sub>OL</sub> = 24 mA		0.22	0.55		0.55	
		4.50	I <sub>OL</sub> = 32 mA		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	1.65 to 5.5	$0 \le V_{IN} \le 5.5 \text{ V}$			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V			1		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> = 5.5 V, GND			1		10	μΑ

# NC7SZ74

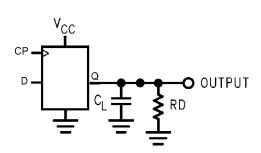
# **AC ELECTRICAL CHARACTERISTICS**

				Т	A = +25°	с <u> </u>	$T_A = -40$	to +85°C	Units Fig	
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min	Тур	Max	Min	Max		Figure
f <sub>MAX</sub>	Maximum Clock	1.80 ±0.15	C <sub>L</sub> = 15 pF,	75			75		MHz	Figure 4
	Frequency	2.50 ±0.20	$R_D = 1 M\Omega$ , $S_1 = Open$	150			150			Figure 8
		3.30 ±0.30	]	200			200			
		5.00 ±0.50		250			250			
		3.30 ±0.50	C <sub>L</sub> = 50 pF,	175			175			
		5.00 ±0.50	$R_D = 500 \Omega$ , $S_1 = Open$	200			200		1	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	1.80 ±0.15	C <sub>L</sub> = 15 pF,		6.5	12.5		13.0	ns	Figure 4
	CK to Q, Q	2.50 ±0.20	$R_D = 1 M\Omega$ , $S_1 = Open$		3.8	7.5		8.0		Figure 6
		3.30 ±0.30	]		2.8	6.5		7.0	1	
		5.00 ±0.50			2.2	4.5		5.0		
		3.30 ±0.30	C <sub>L</sub> = 50 pF,		3.4	7.0		7.5		
		5.00 ±0.50	$R_{D} = 500 \Omega,$ $S_{1} = Open$		2.6	5.0		5.5	1	
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	1.80 ±0.15	C <sub>L</sub> = 15 pF,		6.5	14.0		14.5	ns	Figure 4
	$\overline{\text{CLR}}$ , $\overline{\text{PR}}$ to Q, $\overline{\text{Q}}$	$\overline{\text{CLR}}, \overline{\text{PR}} \text{ to Q}, \overline{\text{Q}}$ 2.50 $\pm 0.20$ $R_L = 1 \text{ M}\Omega, S_1 = \text{Open}$ 3.8 9.0	9.0		9.5	1	Figure 6			
		3.30 ±0.30	] - open		2.8	6.5		7.0	1	
		5.00 ±0.50 2.2 5.0		5.5	1					
		3.30 ±0.30	C <sub>L</sub> = 50 pF,		3.4	7.0		7.5	1	
		5.00 ±0.50	$R_D = 500 \Omega$ , $S_1 = Open$		2.6	5.0		5.5	1	
t <sub>S</sub>	Setup Time CK to D	1.80 ±0.15	C <sub>L</sub> = 15 pF,	6.5			6.5		_	Figure 4
		2.50 ±0.20	$R_L = 1 \text{ M}\Omega, \\ S_1 = \text{Open}$ 3.5 3.5 2.0 2.0 1.5 1.5	3.5			3.5			Figure 7
		3.30 ±0.30		2.0			2.0			
		5.00 ±0.50			]					
		3.30 ±0.30	C <sub>L</sub> = 50 pF,	2.0			2.0			
		5.00 ±0.50	$R_D = 500 \Omega$ , $S_1 = Open$	1.5			1.5			
t <sub>H</sub>	Hold Time, CK to D	1.80 ±0.15	C <sub>L</sub> = 15 pF,	0.5			0.5		ns	Figure 4
		2.50 ±0.20	$R_L = 1 M\Omega$ , $S_1 = Open$	0.5			0.5		1	Figure 7
		3.30 ±0.30	31 = Open	0.5			0.5			
		5.00 ±0.50		0.5			0.5			
		3.30 ±0.30	C <sub>L</sub> = 50 pF,	0.5			0.5		1	
		5.00 ±0.50	$R_D = 500 \Omega$ , $S_1 = Open$	0.5			0.5		1	
t <sub>W</sub>	Pulse Width, CK,	1.80 ±0.15	C <sub>L</sub> = 15 pF,	6.0			6.0		ns	Figure 4
	PR, CLR	2.50 ±0.20	$R_L = 1 M\Omega$ , $S_1 = Open$	4.0			4.0		1	Figure 8
		3.30 ±0.30	o <sub>1</sub> = Open	3.0			3.0			
		5.00 ±0.50	1	2.0			2.0		1	
		3.30 ±0.30	C <sub>L</sub> = 50 pF,	3.0			3.0		1	
		5.00 ±0.50	$R_D = 500 \Omega$ , $S_1 = Open$	2.0			2.0			
t <sub>REC</sub>	Recover Time CLR,	1.80 ±0.15	C <sub>L</sub> = 15 pF,	8.0			8.0		ns	Figure 7
.123	PR to CK	2.50 ±0.20	$R_L = 1 M\Omega$ , $S_1 = Open$	4.5	1		4.5		1	
		3.30 ±0.30	_ o <sub>1</sub> = open	Open 3.0 3.0	1					
		5.00 ±0.50	-	3.0			3.0		1	
		3.30 ±0.30	C <sub>L</sub> = 50 pF,	3.0			3.0		1	
		5.00 ±0.50	$R_{D} = 500 \Omega,$ $S_{1} = Open$	3.0			3.0			

## AC ELECTRICAL CHARACTERISTICS (continued)

				T <sub>A</sub> = +25°C		T <sub>A</sub> = -40 to +85°C				
Symbol	Parameter	V <sub>CC</sub>	Conditions	Min	Тур	Max	Min	Max	Units	Figure
C <sub>IN</sub>	Input Capacitance	0			3				pF	
C <sub>OUT</sub>	Output Capacitance	0			4				pF	
C <sub>PD</sub>	Power Dissipation	3.30			10				pF	
	Capacitance (Note 1)	5.00			12					

1. CPD is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (ICCD) at no output loading and operating at 50% duty cycle. CPD is related to I<sub>CCD</sub> dynamic operating current by the expression:  $I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC}static).$ 



2.  $C_L$  includes load and stray capacitance. Input PRR = 1.0 MHz  $t_{\rm W}$  = 500 ns.

Figure 2. AC Test Circuit

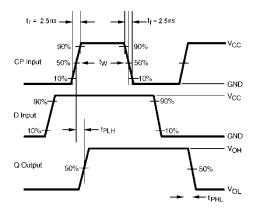
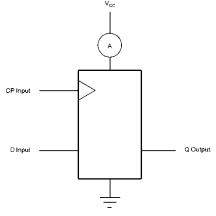


Figure 4. AC Waveforms



- 3. CP input = AC Waveforms  $t_r = t_f = 2.5 \text{ ns.}$
- 4. CP input PRR = 10 MHz; Duty Cycle = 50%.
  5. D input PRR = 5 MHz; Duty Cycle = 50%.

Figure 3. AC Test Circuit

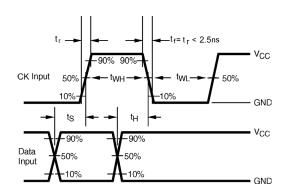


Figure 5. AC Waveforms

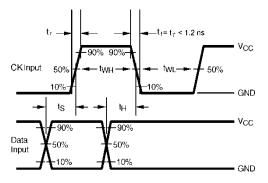


Figure 6. AC Waveforms

## NC7SZ74

# **ORDERING INFORMATION**

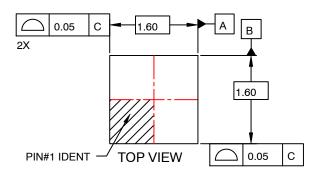
Part Number	Top Mark	Package	Packing Method <sup>†</sup>
NC7SZ74K8X	SZ74	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3000 Units on Tape & Reel
NC7SZ74K8X-L22236	SZ74	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3000 Units on Tape & Reel
NC7SZ74L8X	N9	8-Lead MicroPak, 1.6 mm Wide	5000 Units on Tape & Reel
NC7SZ74L8X-L22185	N9	8-Lead MicroPak, 1.6 mm Wide	5000 Units on Tape & Reel

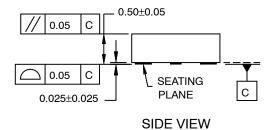
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

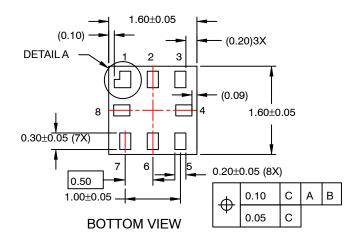
MicroPak is a trademark of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries.

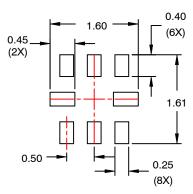
UQFN8 1.6X1.6, 0.5P CASE 523AY ISSUE O

**DATE 31 AUG 2016** 





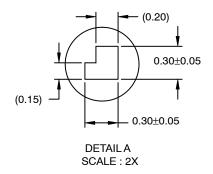




RECOMMENDED LAND PATTERN

#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

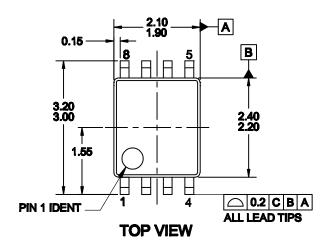


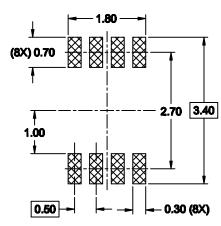
DOCUMENT NUMBER:	98AON13591G	Electronic versions are uncontrolled except when accessed directly from the Document Repository Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	UQFN8 1.6X1.6, 0.5P		PAGE 1 OF 1			

ON Semiconductor and a retrademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

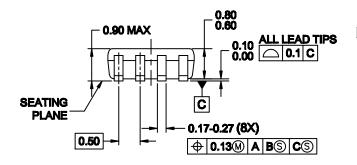
US8 CASE 846AN ISSUE O

**DATE 31 DEC 2016** 





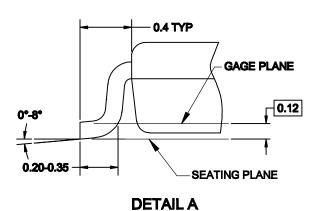
# RECOMMENDED LAND PATTERN

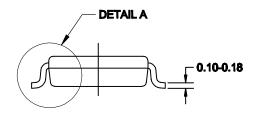


# **NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-187
- **B. DIMENSIONS ARE IN MILLIMETERS.**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.

# **SIDE VIEW**





DOCUMENT NUMBER:	98AON13778G	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	US8		PAGE 1 OF 1			

ON Semiconductor and a re trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMi., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer p

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative